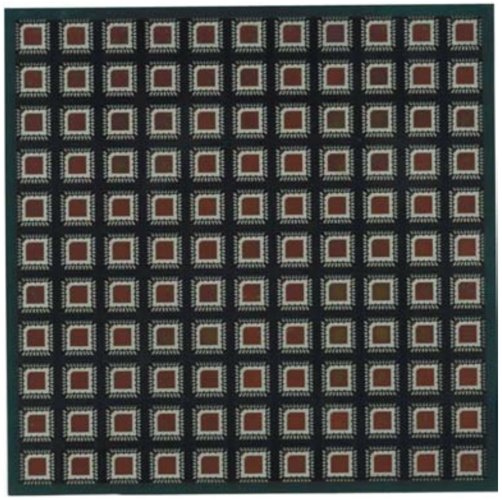
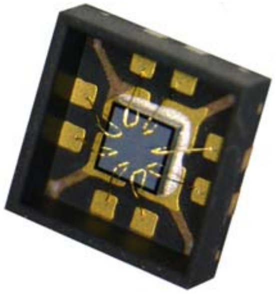
Cu Leadframe Construction



Copper Leadframe with pre-molded cavity array.
Shown before sawing.

Flat Lids, covers and Dome Lids available

Wire bond your die in the open cavity



1.0 mil Gold or Aluminum Wire
Plated Ni Pd Au - Copper Lead Frame

USA Distributed by:
TopLine
(800) 776-9888
sales@topline.tv

International Distributors:

Scandinavia:
Kenneth Hedman
GB Tech
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Tel +972-9-748-0130

Belgium – Netherlands:
Tom Gevers
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S.K. Kang
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Singapore, Malaysia, China:
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Dou Yee Enterprises
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Switzerland:
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+41 (0)56 483 25 02

France:
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Poland:
Jacek Tomaszeswski
Semicon
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India:
L. Sampath
EMST Marketing PVT
Tel +91 (020) 3250 1000

China:
Jenny Gao
Universal Enterprise
Tel: +852 2771 1286

Turkey:
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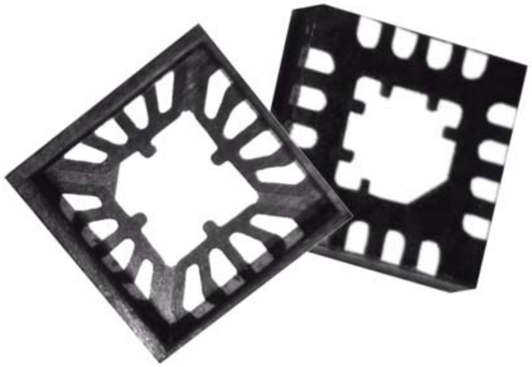
Open Cavity
Air Cavity
M-QFN Package



Applications:

- Fabless Prototype
- Socket Probing
- RF Microwave
- MEMS

www.MirrorSemi.com

Package Dimension Table

Open Tooled

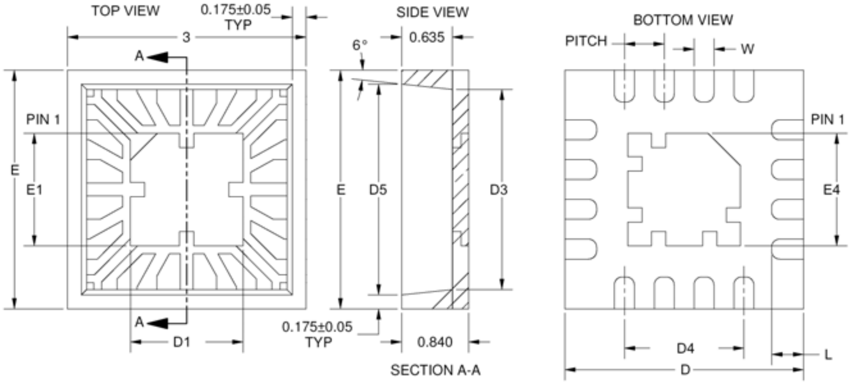
Pins	Pitch	Body D/E	Die Pad D1/E1	M-QFN DWG Nbr
8	0.65mm	3x3mm	1.4mm	460850
12	0.5mm	3x3mm	1.4mm	451260
16	0.5mm	3x3mm	1.4mm	451660
16	0.65mm	4x4mm	2.4mm	461650
20	0.5mm	4x4mm	2.4mm	452050
24	0.5mm	4x4mm	2.4mm	452460
32	0.5mm	5x5mm	3.4mm	453260
40	0.4mm	5x5mm	3.4mm	444050
40	0.5mm	6x6mm	4.4mm	454060
48	0.4mm	6x6mm	4.4mm	444850
48	0.5mm	7x7mm	5.4mm	454860
56	0.5mm	8x8mm	6.4mm	455650
64	0.5mm	9x9mm	7.4mm	456450
72	0.5mm	10x10mm	8.4mm	457250
80	0.5mm	12x12mm	10.4mm	458050

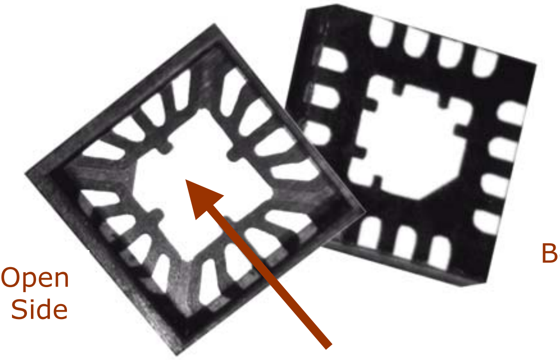
Road Map – Call for Details

Pins	Pitch	Body D/E	Die Pad D1/E1	DWG Nbr
12	0.65mm	4x4mm	2.4mm	461250
12	0.8mm	4x4mm	2.4mm	481250
16	0.8mm	5x5mm	3.4mm	481650
20	0.4mm	3x3mm	1.4mm	442050
20	0.65mm	5x5mm	3.4mm	462050
24	0.65mm	5x5mm	3.4mm	462450
24	0.8mm	6x6mm	4.4mm	482450
28	0.4mm	4x4mm	2.4mm	442850
28	0.5mm	5x5mm	3.4mm	452850
28	0.65mm	6x6mm	4.4mm	462850
28	0.8mm	7x7mm	5.4mm	482850
32	0.4mm	5x5mm	3.4mm	443250
32	0.65mm	7x7mm	5.4mm	463250
32	0.8mm	8x8mm	6.4mm	483250
36	0.4mm	5x5mm	3.4mm	443650
36	0.5mm	6x6mm	4.4mm	453650
40	0.65mm	8x8mm	6.4mm	464050
44	0.5mm	7x7mm	5.4mm	454450
44	0.65mm	8x8mm	6.4mm	464450
52	0.5mm	8x8mm	6.4mm	455250
56	0.4mm	7x7mm	5.4mm	445650
64	0.4mm	8x8mm	6.4mm	445650
68	0.4mm	8x8mm	6.4mm	446850
68	0.5mm	10x10mm	8.4mm	456850
72	0.4mm	9x9mm	7.4mm	447250
76	0.4mm	9x9mm	7.4mm	447650
88	0.4mm	10x10mm	8.4mm	448850
100	0.4mm	12x12mm	10.4mm	449950

Air Open Cavity M-QFN Series

Mirror Semiconductor™





Open Cavity Side

Bottom

Attach your die here.
Add flat lid or glob top.

Applications:

- **Fabless Prototype**
- **Low Volume Builds**
- **Socket Probing**
- **RF Microwave**
- **MEMS**

Mirror Semiconductor, Inc
17595 Harvard Ave, Suite 509
Irvine, CA 92614 USA
info@MirrorSemi.com

www.MirrorSemi.com

Tel 1- 866-404-8800

Rev 2011 Aug 6